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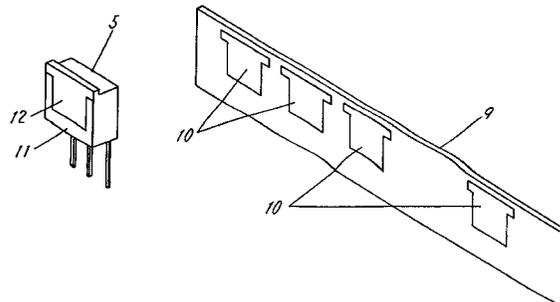
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(54) **ELECTRONIC EQUIPMENT**

(57) Electronic equipment comprising a wiring board, electronic component mounted on the wiring board and having a heat dissipation portion on the surface thereof, and an insulating heat dissipation plate thermally connected to the electronic component, wherein the heat dissipation portion is directly connected to the heat dissipation plate with heat conductive bonding materials. The heat dissipation plate is a ceramic plate having at least one land for connecting electronic component or a resin plate containing highly heat conductive material. By directly connecting the insulating heat dissipation plate to electronic component generating heat, an insulating plate between the heat dissipation plate and the electronic component used in a conventional method becomes not required. Consequently, it is possible to enhance a heat dissipation effect of electronic component in electronic equipment.

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FIG. 2



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